

RFSW6042

Product Qualification Report SW6042-PQ030, Revision A

Product Description: SP4T Switch

Package Type: 1.8mm x 1.8mm QFN

Process Technology: SOI CMOS

Qualification Number: 12-QUAL-1771

Date issued: 09/16/2013

FOR IMPORTANT INFORMATION REGARDING THESE MATERIALS INCLUDING DISCLAIMERS REGARDING USE IN CERTAIN APPLICATIONS, SEE STANDARD DISCLAIMER FOR PRODUCT DOCUMENTS

Test Name	Test Standard and Conditions	# Samples x # Lots	Test Results
High Temperature Operating Life	JESD22-A108 125°C, 1000 hours	77x3 lots	Pass
Highly-Accelerated Temperature and Humidity Stress Test	JESD22-A110 110°C / 85% RH / 122 kPa, 264 hours	77x3 lots	Pass
ESD Human Body Model	JS-001-2010	3x1 lot	Class 2
ESD Charged Device Model	JESD22-C101	3x1 lot	Class IV
Moisture Sensitivity Level	J-STD-020 3x Cumulative Reflow at 260°C MSL2	77x3 lots	Pass
Temperature Cycling	JESD22-A104 Condition B: -55° to +125°C Soak Mode 1, 700 Cycles Preconditioning per JESD22-A113 MSL2	77x3 lots	Pass
Temperature Cycling (On Board)	JESD22-A104 Condition G: -40° to +125°C Soak Mode 2, 850 Cycles Preconditioning per JESD22-A113 MSL2	77x3 lots	Pass
High Temperature Storage	JESD22-A103 150°C, 1000 hours 3x Reflow Preconditioning per J-STD-020	77x3 lots	Pass
Accelerated Moisture Resistance – Unbiased HAST	JESD22-A118 110°C / 85% RH / 122 kPa, 264 hours Preconditioning per JESD22-A113 MSL3	77x3 lots	Pass
Solderability	JESD22-B102 Condition E: 16 Hour Dry Bake Pb-Free Process, Method 1: Dip and Look	77x3 lots	Pass
Drop Shock	JESD22-B111	15x3 boards	Pass
Conclusion	This part meets RFMD's product qualification requirements		

Sample size and lot quantities reported are the minimum required for this qualification.